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# **PROTECTION PRODUCTS - Z-Pak™**

#### Description

µClamp<sup>®</sup> TVS diodes are designed to protect sensitive electronics from damage or latch-up due to ESD. They are designed to replace 0201 size multilayer varistors (MLVs) in portable applications such as cell phones, notebook computers, and other portable electronics. They feature large cross-sectional area junctions for conducting high transient currents. These devices offer desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

µClamp<sup>®</sup>0551Y features extremely good ESD protection characteristics highlighted by low typical dynamic resistance of 0.37 Ohms, low peak ESD clamping voltage, and high ESD withstand voltage (+/-20kV contact per IEC 61000-4-2). Low typical capacitance (6.9pF at VR=0V) minimizes loading on sensitive cirucuits. Each device will protect one data or power line operating at 5 Volts.

 $\mu$ Clamp0551Y is in a 2-pin SLP0603P2X3E package measuring 0.6 x 0.3 mm with a nominal height of 0.25mm. Leads are finished with lead-free NiAu. The small package gives the designer the flexibility to protect single lines in applications where arrays are not practical. The combination of small size and high ESD surge capability makes them ideal for use in portable applications such as cellular phones, digital cameras, and tablet PC's.

#### **Features**

- High ESD withstand Voltage: +/-20kV (Contact/Air) per IEC 61000-4-2
- Able to withstand over 1000 ESD strikes per IEC 61000-4-2 Level 4
- Ultra-small 0201 package
- Protects one data or power line
- Low reverse current: <3nA typical (VR=5V)</li>
- Working voltage: +/- 5V
- Low capacitance: 6.9pF typical
- Extremely low dynamic resistance: 0.37 Ohms (Typ)
- Solid-state silicon-avalanche technology

#### Mechanical Characteristics

- SLP0603P2X3E Package
- Pb-Free, Halogen Free, RoHS/WEEE Compliant
- Nominal Dimensions: 0.6 x 0.3 x 0.25 mm
- Lead Finish: NiAu
- Marking: Marking Code
- Packaging: Tape and Reel

#### Applications

- Cellular Handsets & Accessories
- Keypads, Side Keys, Audio Ports
- Portable Instrumentation
- Digital Lines
- Tablet PC

#### **Nominal Dimensions**



# Schematic



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## **PROTECTION PRODUCTS**

Absolute Maximum Rating					
Rating	Symbol	Value	Units		
Peak Pulse Power (tp = 8/20µs)	P <sub>pk</sub>	30	Watts		
Maximum Peak Pulse Current (tp = 8/20µs)	l <sub>pp</sub>	2.5	Amps		
ESD per IEC 61000-4-2 $(Air)^1$ ESD per IEC 61000-4-2 $(Contact)^1$	V <sub>esd</sub>	+/- 20 +/- 20	kV		
Operating Temperature	T,	-40 to +125	°C		
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C		

# Electrical Characteristics (T=25°C)

Parameter	Symbol	Conditions	Minimum	Typical	Maximum	Units
Reverse Stand-Off Voltage	V <sub>RWM</sub>	Pin 1 to 2 or 2 to 1			5	V
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>t</sub> = 1mA Pin 1 to 2 or 2 to 1	6	8	9.5	V
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> = 5V, T=25°C Pin 1 to 2 or 2 to 1		3	50	nA
Clamping Voltage	V <sub>c</sub>	I <sub>pp</sub> = 1A, tp = 8/20μs Pin 1 to 2 or 2 to 1			11	V
Clamping Voltage	V <sub>c</sub>	I <sub>pp</sub> = 2.5A, tp = 8/20µs Pin 1 to 2 or 2 to 1			12	V
ESD Clamping Voltage <sup>2</sup>	V <sub>c</sub>	IPP = 4A, tIp = 0.2/100ns		9.5		V
ESD Clamping Voltage <sup>2</sup>	V <sub>c</sub>	IPP = 16A, tlp = 0.2/100ns		14		V
ESD Clamping Voltage <sup>2</sup>	V <sub>c</sub>	IPP = 30A, tIp = 0.2/100ns		18.5		V
ESD Peak Clamping Voltage <sup>2</sup>	V <sub>c</sub> max	+/-8kV Contact per IEC 6100-4-2		+/-35		V
Dynamic Resistance <sup>2, 3</sup>	R <sub>D</sub>	tp = 100ns		0.37		Ohms
Junction Capacitance	C	$V_{R} = 0V$ to 5V, f = 1MHz		6.9	9	pF

Notes

1)ESD gun return path connected to ESD ground reference plane.

2)Transmission Line Pulse Test (TLP) Settings:  $t_p = 100ns$ ,  $t_r = 0.2ns$ ,  $I_{TLP}$  and  $V_{TLP}$  averaging window:  $t_1 = 70ns$  to  $t_2 = 90ns$ .

3) Dynamic resistance calculated from  $I_{TLP} = 4A$  to  $I_{TLP} = 16A$ 



#### **Typical Characteristics**

#### Non-Repetitive Peak Pulse Power vs. Pulse Time

Clamping Voltage vs. Peak Pulse Current (tp=8/20us)











**Typical Characteristics** 

**Typical Insertion Loss S21** 



#### **Applications Information**

#### **Assembly Guidelines**

The small size of this device means that some care must be taken during the mounting process to insure reliable solder joint. The table below provides Semtech's recommended assembly guidelines for mounting this device. The figure at the right details Semtech's recommended aperture based on the below recommendations. Note that these are only recommendations and should serve only as a starting point for design since there are many factors that affect the assembly process. The exact manufacturing parameters will require some experimentation to get the desired solder application.

Assembly Parameter	Recommendation		
Solder Stencil Design	Laser cut, Electro-polished		
Aperture shape	Rectangular with rounded corners		
Solder Stencil Thickness	0.100 mm (0.004")		
Solder Paste Type	Type 4 size sphere or smaller		
Solder Reflow Profile	Per JEDEC J-STD-020		
PCB Solder Pad Design	Non-Solder mask defined		
PCB Pad Finish	OSP OR NiAu		



#### **Recommended Mounting Pattern**





# Outline Drawing - SLP0603P2X3E



# Land Pattern - SLP0603P2X3E





# Marking Code



# Ordering Information

Part Number	Qty per	Pocket	Reel
	Reel	Pitch	Size
uClamp0551Y.TFT	15,000	2mm	7 Inch

Note:

MicroClamp, uClamp and  $\mu Clamp$  are trademarks of Semtech Corporation

Note:

Device is electrically symmetrical

# **Carrier Tape Specification**



NOTES: ALL DIMENSIONS IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.



**Device Orientation in Tape** 



# Contact Information

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